

BS EN 60749-20-1:2009



# BSI British Standards

## Semiconductor devices – Mechanical and climatic test methods —

Part 20-1: Handling, packing, labelling and shipping of surface-mount devices sensitive to the combined effect of moisture and soldering heat

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This British Standard is the UK implementation of EN 60749-20-1:2009. It is identical to IEC 60749-20-1:2009.

The UK participation in its preparation was entrusted to Technical Committee EPL/47, Semiconductors.

A list of organizations represented on this committee can be obtained on request to its secretary.

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### **Amendments issued since publication**

<b>Amd. No.</b>	<b>Date</b>	<b>Text affected</b>
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**Semiconductor devices -  
Mechanical and climatic test methods -  
Part 20-1: Handling, packing, labelling and shipping  
of surface-mount devices sensitive to the combined effect  
of moisture and soldering heat  
(IEC 60749-20-1:2009)**

Dispositifs à semiconducteurs -  
Méthodes d'essais mécaniques  
et climatiques -  
Partie 20-1: Manipulation, emballage,  
étiquetage et transport des composants  
pour montage en surface sensibles  
à l'effet combiné de l'humidité  
et de la chaleur de brasage  
(CEI 60749-20-1:2009)

Halbleiterbauelemente -  
Mechanische und klimatische  
Prüfverfahren -  
Teil 20-1: Handhabung, Verpackung,  
Kennzeichnung und Transport  
oberflächenmontierbarer Bauelemente,  
die empfindlich gegen die Kombination  
von Feuchte und Lötwärme sind  
(IEC 60749-20-1:2009)

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